



## PRODUCT DATASHEET

# PMT-16 – Compact Metal Wafer Electroplating System

Our most **compact precision plating** system suitable for prototyping or small-scale production. The PMT-16 can be used for plating with standard metals and alloys such as nickel, copper, zinc, etc. It is ideal for **precious metal plating** where solution volume is a critical cost factor. The PMT-16 is designed for bench or table-top placement.



**Precious Metals/ Alloys**  
Gold | Silver | Tungsten  
Palladium | Rhodium

**Standard Metals/ Alloys**  
Nickel | Copper | Zinc | Tin



## Features

- Small footprint
- Compact, single cell
- High flow rate
- Efficient filtration
- Easy process maintenance
- Easy operator interface
- Precision digital microprocessor control
- Suitable for all standard plating metals, eg. copper, nickel, tin, and zinc and their alloys.
- Small solution volume size ideal for precious metal plating:



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**Specifications\***

\*All systems are built to order; specs shown is standard build

<b>Construction</b>	<b>Polypropylene</b>
<b>Dimensions</b>	Width: 22 <sup>3/4</sup> " (580mm) Height: 50 " (1300mm) Depth: 32" (815mm)
<b>Wafer Dimension Standard</b>	4", 6" and 8" (101.6, 152.3 and 203.2mm)
<b>Total Solution Volume</b>	<4 gallons – 7.5 gallons (15 – 28 liters)
<b>Heaters</b>	0.5 kW
<b>Cooling</b>	Teflon cooling coil
<b>Cells</b>	Single cell (1)
<b>Pump</b>	1/15 hp
<b>Rectifier</b>	27 A, 24 VDC (options available)
<b>Filtration</b>	1 stage, 5 micron DOE, 10"
<b>Flow</b>	5 lpm max per cell (adjustable)
<b>Alarm</b>	High level and low level protection
<b>Instrumentation</b>	Temperature controller: ±1° dual setpoint
<b>UTILITIES</b>	
<b>Electrical</b>	200/220 VAC, 1 phase, 6 kVA, 50-60 Hz
<b>Di Water</b>	Di Water: >17 meg-ohm, 1/2", 4 gpm on demand
<b>Cooling</b>	11 lph, pressure 45-60 psi, Temp ~12°C (53°F)
<b>Exhaust</b>	400 CFM 3½" outside diameter

